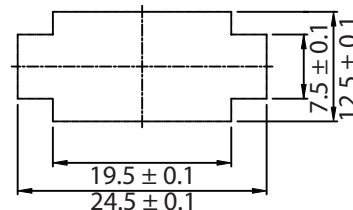
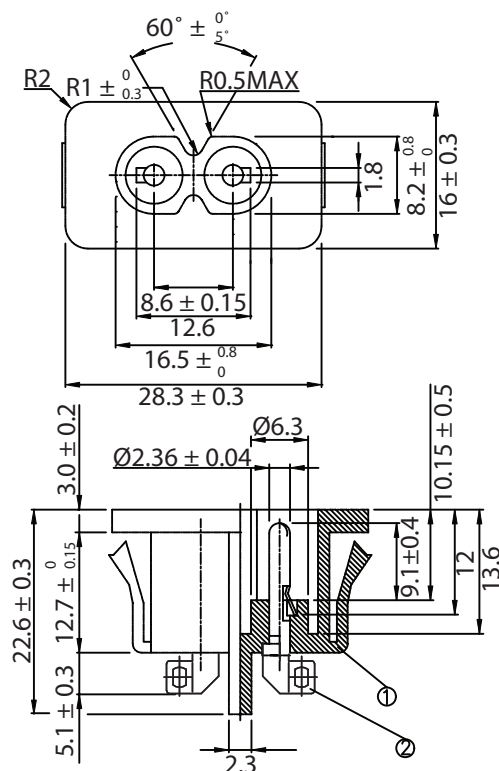
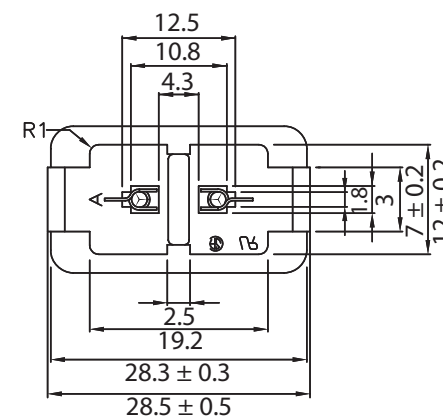
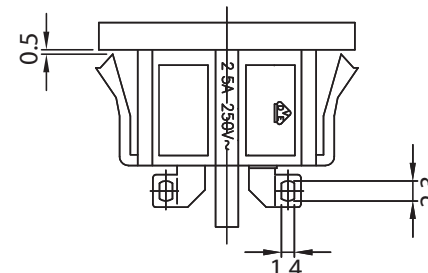
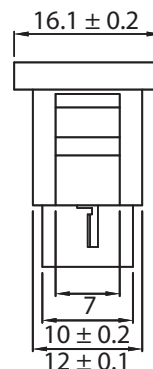


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REVISION			
REV.	DESCRIPTION	DATE	APPROVED
A	Panel Thickness 0.8~1.1	01-28-03	BZ
B	Panel Thickness 0.6~2.0	07-15-03	LG
C	Panel Thickness 0.6~1.5	10-30-03	LG
D	RoHS Compliancy	06-01-06	DP
E	Dimensions Update	09-14-07	DP



PANEL CUTOUT



NOTES:

MATERIAL:

HOUSING: THERMOPLASTIC
 TERMINAL: COPPER ALLOY
 RATING: 2.5A 250V AC
 INSULATION RESISTANCE: OVER 100 OHM, 500V DC
 DIELECTRIC STRENGTH: 2000V AC ONE MINUTE
 APPROVALS: UL, CSA, VDE
 PANEL THICKNESS: 0.6~1.5
 RoHS COMPLIANT

CONTROLLED

2	Contact PIN Bronze Strip t=0.3mm Tin-Plated	2		
1	Body Insulator PC	1		
Dim range (mm)	Tolerance +/- (mm)	Qualtek Electronics Corp. PPC DIVISION		
		Part Number: 771W-X2/01	RoHS Compliant	
0-1	0.15	Description: AC RECEPTACLE		
1-6	0.20			
6-18	0.30	UNIT: mmREV. E		
18-50	0.50			
50-120	0.70	Drawn / Date	Checked / Date	Approved / Date
120-250	0.90	B.Zhang 03-10-04	03-10-04	JJH / 03-10-04
250-500	1.20			